



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit: 2818

Examiner: NGUYEN, THINH T

In Re PATENT APPLICATION Of:

Applicant : Naofumi IWAMATO

Serial No. : 10/717,655

Filed : November 21, 2003

For : METHOD OF MANUFACTURING  
SEMICONDCUTOR CHIP HAVING  
SUPPORTING MEMBER AND  
SEMICONDCUTOR PACKAGE HAVING  
THE SEMICONDCUTOR CHIP

Attorney Ref. : F00ED0440-DIV

**INFORMATION  
DISCLOSURE  
STATEMENT**

August 5, 2004

Commissioner for Patents  
P. O. Box 1450  
Alexandria, VA 22313-1450

Sir:

This is an Information Disclosure Statement submitted in compliance with the timing requirements of 37 C.F.R. § 1.97(C)(2). In the first Action, Applicant was required to put the IDS in correct USPTO form in this communication because of informality of the IDS. Attached are copies of FIVE Japanese laid open patent publications and two US patent publications. These publications are listed on the attached Form PTO-1449. English language abstracts or translations for each Japanese laid open patent publication are also attached.

Consideration of the submitted documents is respectfully requested.

Respectfully submitted,

08/06/2004 YPOLITE1 00000041 500945 10717655

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<b>FORM PTO-1449</b> <b>INFORMATION DISCLOSURE STATEMENT</b>	Atty Docket F00ED0440-DIV	U.S. Application No.: 10/717,655
	Applicant Naofumi IWAMOTO	
	U.S. Filing Date: July 18, 2002	Group 2818

**U.S. PATENT DOCUMENTS**

Examiner Initial		Document Number	Date	Name	Class	Sub-Class	Filing Date
	AA	6,208,022B1	03-2001	Tamura	257	692	03/26/98
	AB	5,635,756	06-1997	Kohno et al.	257	676	01/06/95
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						

**-OREIGN PATENT DOCUMENTS**

		Document Number	Pub. Date	Country	Class	Sub-Class	Translation
	AL	Laid open patent Pub. 11-87423	03/30/99	Japan	H01L	21/60	Abstract
	AM	Laid open patent Pub. 2001-110951	04/20/01	Japan	H01L	23/34	Abstract
	AN	Laid open patent Pub. 8-46313	02/16/96	Japan	H05K	1/14	Translation
	AO	Laid open patent Pub. 2000-195900	7/14/00	Japan	H01L	21/60	Translation
	AP	Laid open patent Pub. 2000-243785	9/8/00	Japan	H01L	21/60	Translation

**OTHER (Including Author, Title, Date, Pertinent Pages, etc.)**

	AR	
	AS	
Examiner		Date Considered

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.